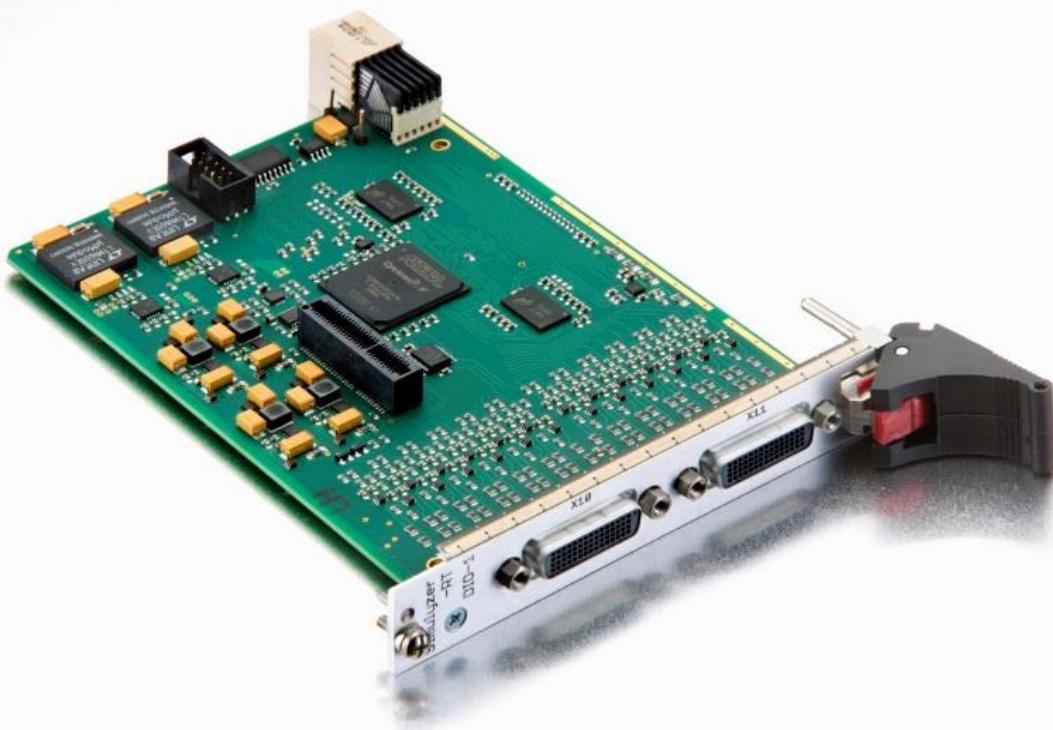


Simulyzer-RT

DIO-1 Card



Hardware version	V1.01_a
Documentation version:	1.2
Created:	(1.0) 03.04.2015
	(1.1) 25.04.2016 Note HF sealing spring
	(1.2) 10.10.2021 Company information edited
Order no.:	1.1002

Safety instructions

To avoid damages to persons and devices the following safety instructions have to be noticed!

- Only qualified personnel are allowed to handle this device!
- Before any handling within the device the current supply has to be switched off!
- During operation the device have to be positioned, that enough air condition is supplied and no small parts can get into the ventilation slots.
- In case of any trouble the system has to be switched de-energized!
- The declared environmental conditions and max. voltage ranges have to be observed!
- To warranty the device remove all dust and dirt in periodically intervals.
- Make sure that the ventilation slots are unobstructed!

Intended use:

The Simulyzer RT DIO-1 card is engineered for measurement and analysis of sensors of a RT proofing system. The field of function of the DIO-1 card is the digital data transfer within the test system (see applications).

- The device is only permitted to use for the intended use.
Any other use results the deletion of the guarantee!

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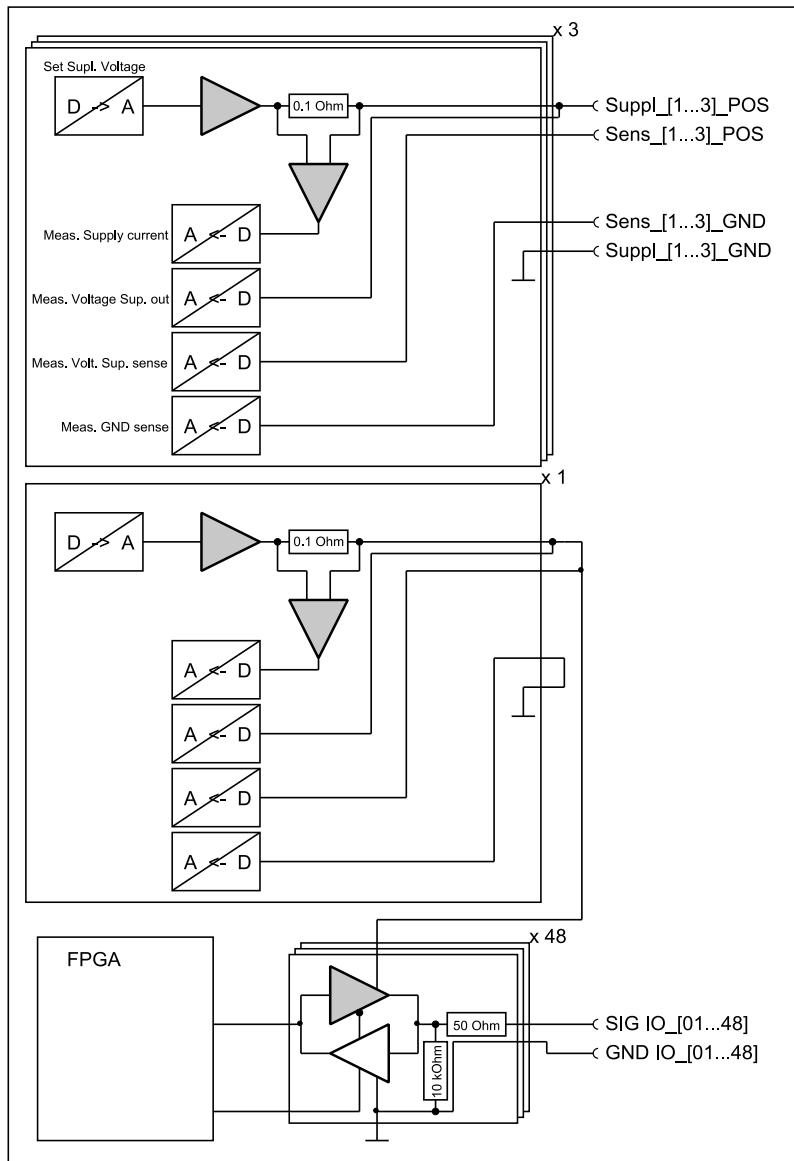
1. Technical data

- Current consumption: 12V / 0,4 A (without external consumers)
- Operating temperature: 0°C ... 40°C (32° F ... 104°F)
- Rel. Humidity: Max. 85% not condensed
- Weight: 150g
- Dimensions: Single Eurocard, 4 U

Test conditions: Environmental temperature 20°C to 26°C (68°F to 78,8°F)

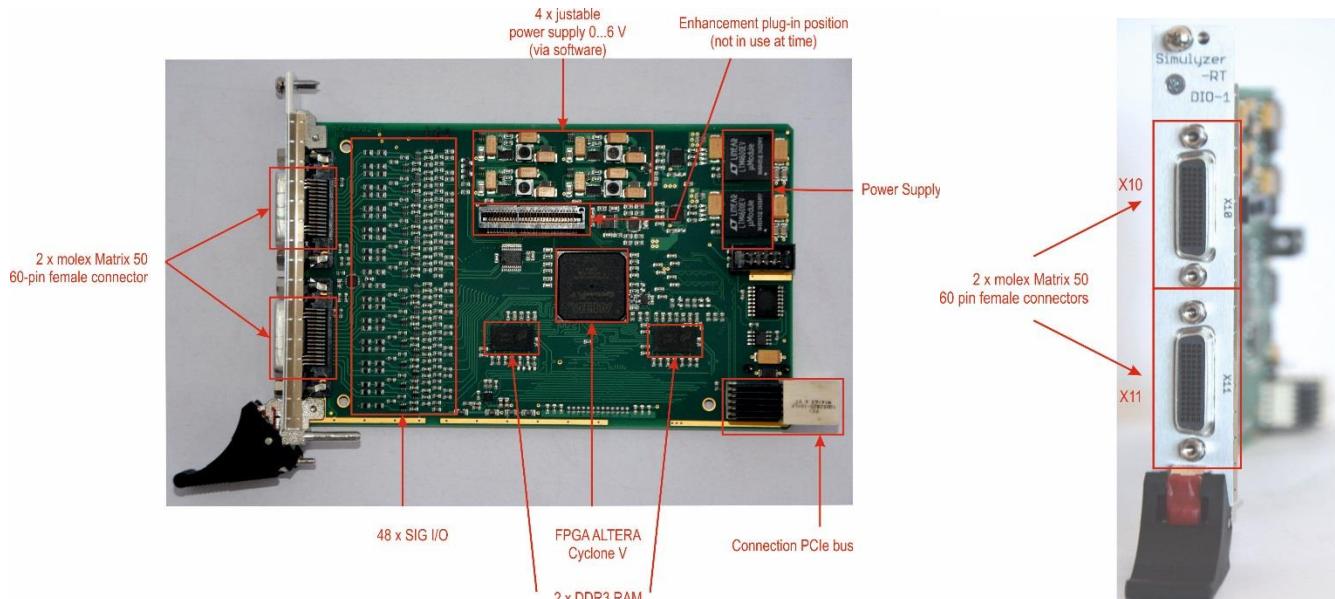
Num	Evaluation	Symbol	typ.	min.	max.	description
1	Permitted voltage range	U_{supp}	12V	11.4V	12.6V	
2	Current consumption	I_{supp}	270mA	-	400mA	Without sensor supply

2. Block diagram



3. Connectors:

- For SPI, FAST-SO
- Connectors to bus: 1 PCIe Lane to CPU-1
Power supply I2C
Parallel to all cards for synchronization
- Connectors frontside: 2x molex „Matrix 50“ 60 pin female connector with dig IO + Sensor Power



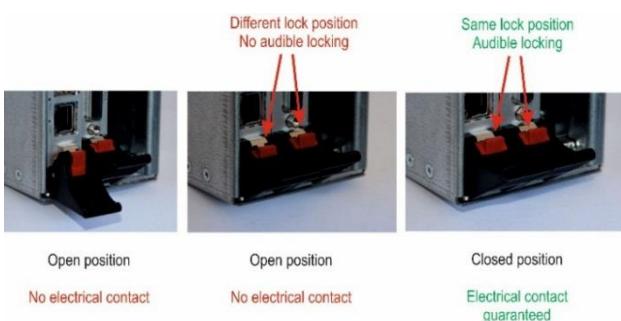
4. Interfaces and FPGA:

- ALTERA FPGA Cyclone V to realize protocolling
- 8 x SPI (MISO, MOSI, CS, CLK) + 16 Reserved DIG IO => 48 Pins
- 16xSPI (16xMISO, 16xMOSI, 8xCS, 8xCLK)/ 48 Pins
- With 16 reserved IO it is possible to realize e.g. 4 x Fast-SO
- All DIG IOs bidirectional, level adjustable from 1.2V to 5.5V operating; max. 20MHz
- 3x adjustable PU outputs,
1.5V to 6.0V, +/- 0.1% of scale final value to supply the sensors,
current limiting 0..1000mA, +/- 0.1%.
- 1x adjustable PU output, 1.5V to 6.0V, +/- 0.1% of scale final value,
current limiting 0..1000mA +/- 0.1%
for internal drivers (+ external)
- 50 Ohm Impedance matching for coaxial cable
- Backward measurement of the 4 PU voltages and the 4 currents, accuracy: +/- 0.1% of scale final value

5. Handling card/chassis

Pay attention that the ejection lever of the plug-in card is arrested correctly.

Only the correct position guarantees a justly connection of the bus system and the power supply!



Note

The forcible insertion of the card with displaced HF-sealing spring will damage them. As a result of that HF energy emission will be increased!

Only with intact HF-sealing spring we guarantee that the whole system confirms to the EMC guidelines.

HF-sealing spring

6. Applications – Working modes

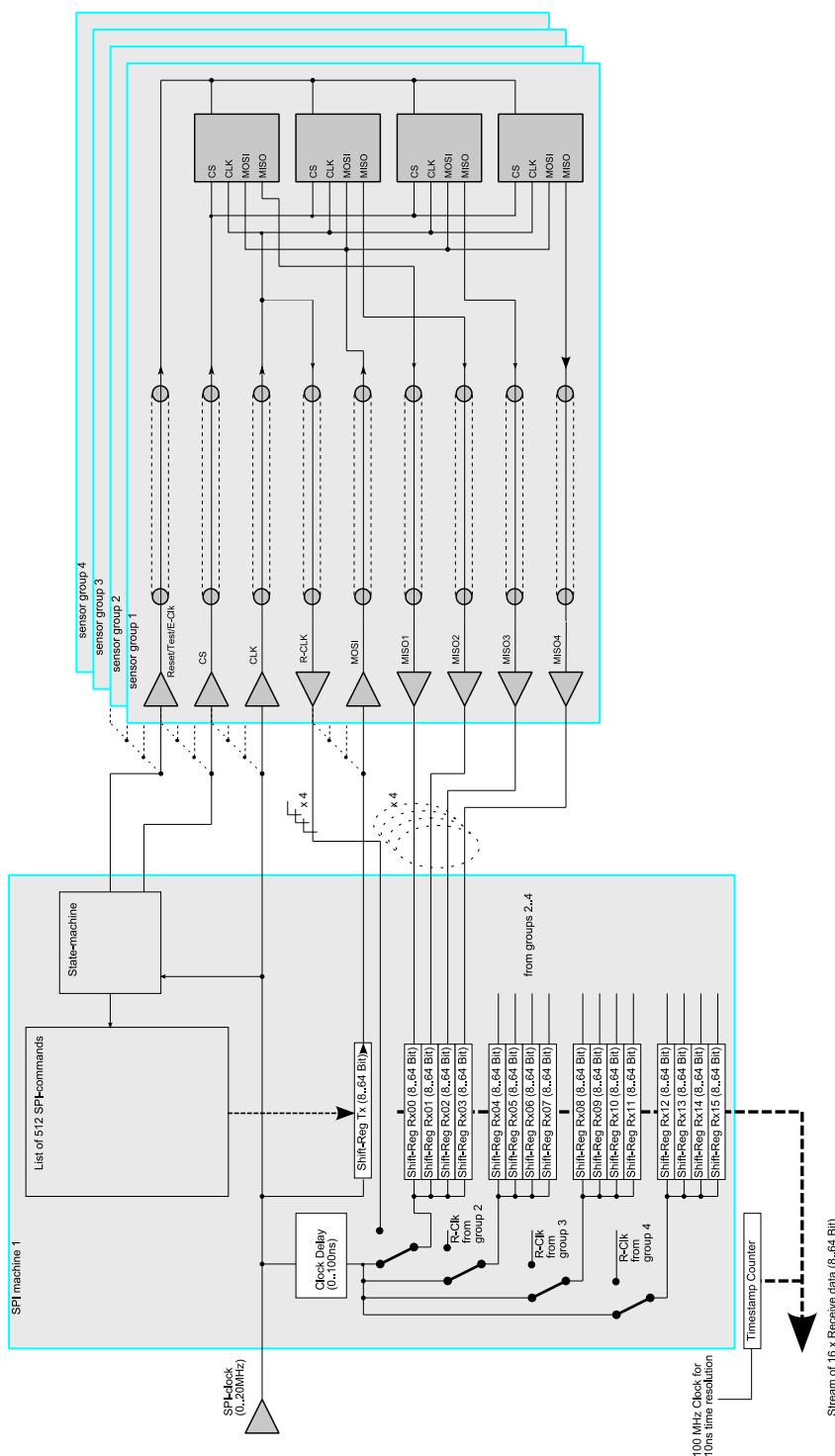
6.1. 16-times highspeed measurement application

To realize an application of 16-times parallel measurement technic a SPI machine is implemented at the FPGA, which controls out of a sending shift register the *Slave-In* of the 16 sensors in common.

Chip-Select, Clock and optionally Reset/Test are also controlled in common.

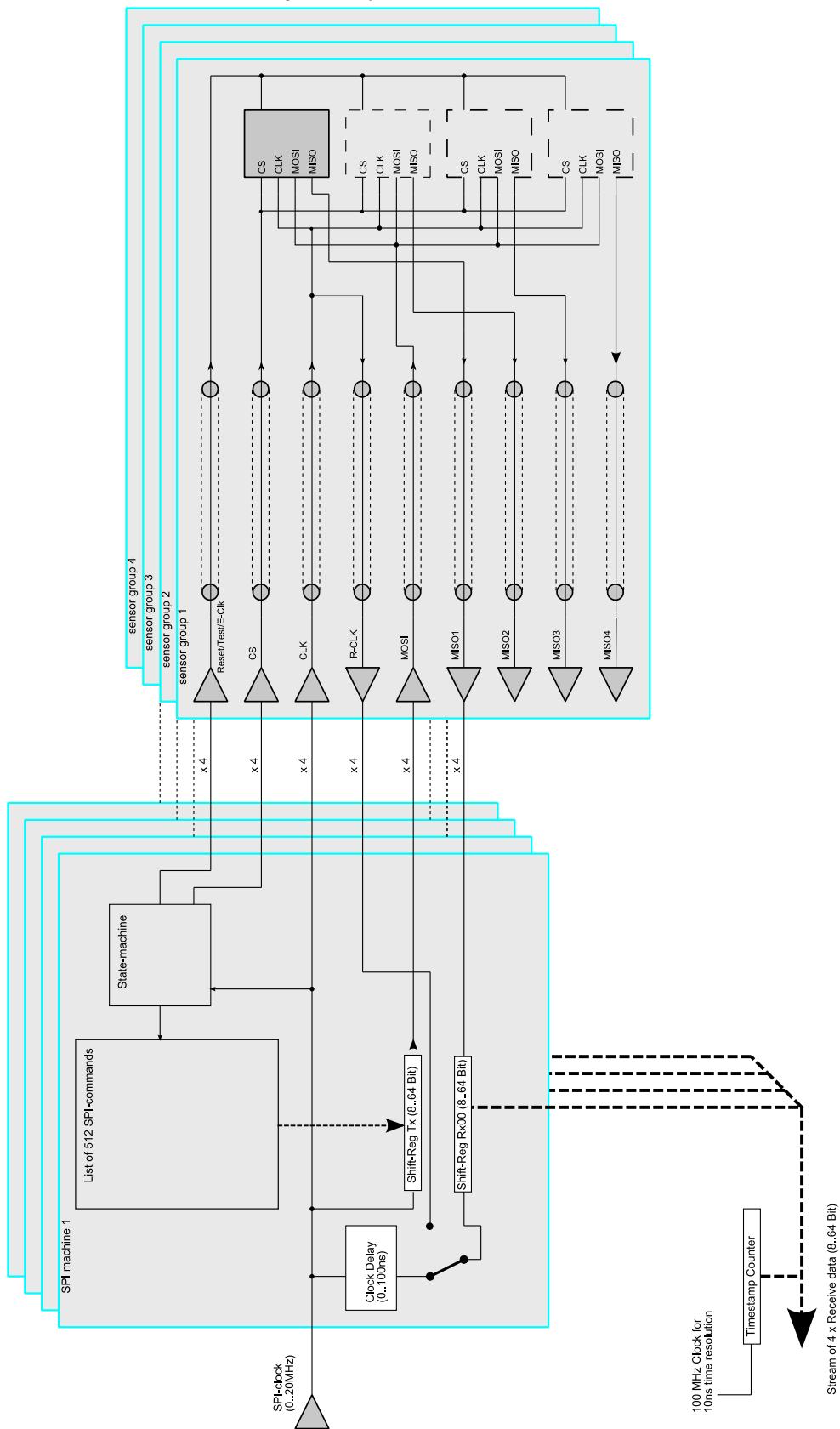
The 16 *Slave-Out* lines are executed individually, which are connected with 16 receiving shift register.

The commands are send absolutely synchronous, the answer are received individually.



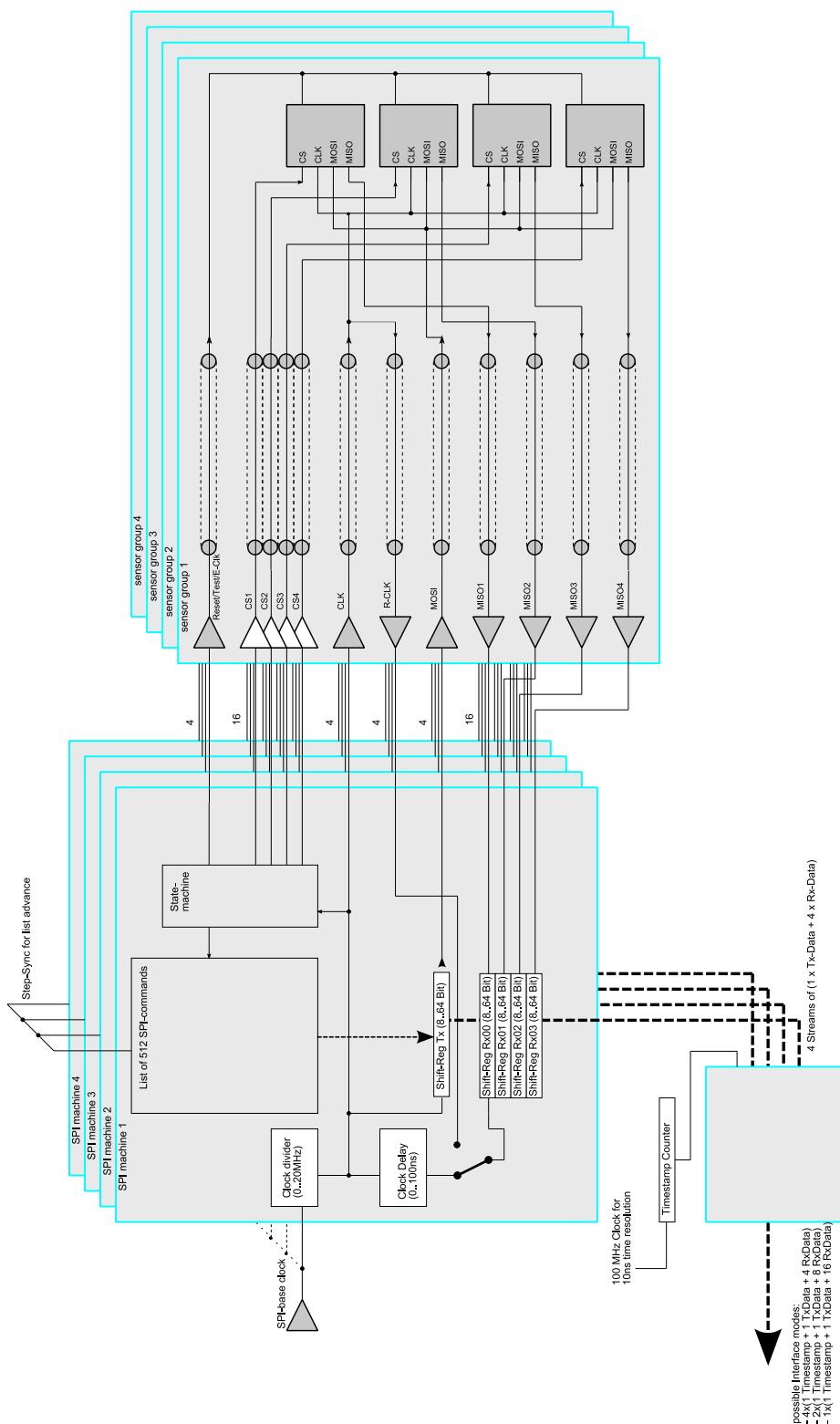
6.2. 4-times comparison application

4 SPI machines each with one own sending- and receiving shift register.
 Each SPI machine serves the first sensor of each 4 times group.
 The rest of the three sensors of each group stay unpopulated.



6.3. 16-times high-speed measurement application with different sensors

At the FPGA four SPI machines are implemented, which each controls the *Slave-In* of 4 sensors of a group in common out of its 4 sending shift register. *Clock* and optionally *Reset/Test* are also controlled in common. Individually executed are the 16 *Slave-Out* lines, which are connected to the 4 receiving shift register of the 4 groups.



7. Measurement accuracy

7.1. Time base

Test conditions: Environmental temperature 20°C to 26°C

Num	Evaluation	Symbol	Type	Max	Unit	Comment
1	Accuracy time base	$\Delta f/f$	± 30	± 50	ppm	-
2	Aging of time base	$\Delta f/f_A$	± 5		ppm/year	-
3	Temperature drift of time base	$\Delta f/f_T$	± 0.3	± 0.7	ppm/°C	-

7.2. Measurement of the supply voltage

Test conditions: Environmental temperature 20°C to 26°C

Num	Evaluation	Symbol	Type	Max	Unit	Comment
4	Accuracy of the measured voltage	U_{mea}	± 0.3	± 0.4	% of scfin. 7.5V	Range 0.5V .. 6.0V
5	Aging of the measured voltage	U_{A-me}		± 0.1	%/year	Range 0.5V .. 6.0V
6	Resolution of the measured voltages		16		Bit	0.. 65535
			0.1144409		mV/LSB	

7.3. Measurement of the supply currents

Test conditions: Environmental temperature 20°C to 26°C

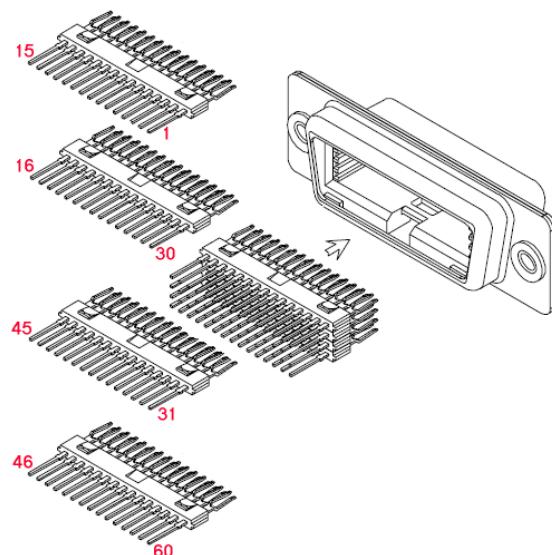
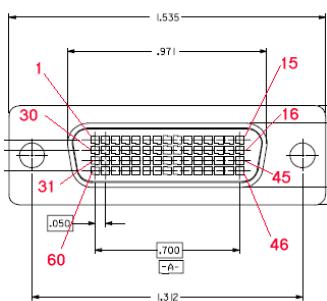
Num	Evaluation	Symbol	Type	Max	Unit	Comment
7	Accuracy of the measured current	I_{mea}	± 0.3	± 0.4	% of scfin. 1000mA	Range 2mA .. 900mA
8	Aging of the measured current	I_{A-me}		± 0.1	% of scfin. 1000mA / year	Range 2mA .. 900mA
9	Resolution of the measured current		16		Bit	0.. 65535
			15,2587891		$\mu A/LSB$	

7.4. Generation of the voltages

Test conditions: Environmental temperature 20°C to 26°C

Num	Evaluation	Symbol	Type	Max	Unit	Comment
10	Accuracy of the created current	U_{mea}	± 0.3	± 0.4	% of scfin. 6.3V	Range 0.5V .. 6.0V
11	Aging of the created current	U_{mea}		± 0.1	% of scfin 6.3V / year	Range 0.5V .. 6.0V
12	Resolution of the created current		16		Bit	0.. 65535
			0,096130371		mV/LSB	

8. Connection diagram X10/X11



Pin	Name X10	Name X11	Cable No.
1	GND IO_01	GND IO_25	K_01
2	SIG IO_01	SIG IO_25	
3	GND IO_02	GND IO_26	K_02
4	SIG IO_02	SIG IO_26	
5	GND IO_03	GND IO_27	K_03
6	SIG IO_03	SIG IO_27	
7	GND IO_04	GND IO_28	K_04
8	SIG IO_04	SIG IO_28	
9	GND IO_05	GND IO_29	K_05
10	SIG IO_05	SIG IO_29	
11	GND IO_06	GND IO_30	K_06
12	SIG IO_06	SIG IO_30	
V _{DG} Sesonor	Sens_1_GND	Sens_3_GND	K_07
	Suppl_1_GND	Suppl_3_GND	K_08
	Suppl_1_GND	Suppl_3_GND	
	Sens_1_POS	Sens_3_POS	K_09
	Suppl_1_POS	Suppl_3_POS	
	Suppl_1_POS	Suppl_3_POS	K_10
19	GND IO_07	GND IO_31	K_11
20	SIG IO_07	SIG IO_31	
21	GND IO_08	GND IO_32	K_12
22	SIG IO_08	SIG IO_32	
23	GND IO_09	GND IO_33	K_13

24	SIG IO_09	SIG IO_33		
25	GND IO_10	GND IO_34	K_14	
26	SIG IO_10	SIG IO_34		
27	GND IO_11	GND IO_35	K_15	
28	SIG IO_11	SIG IO_35		
29	GND IO_12	GND IO_36	K_16	
30	SIG IO_12	SIG IO_36		
31	GND IO_13	GND IO_37	K_17	
32	SIG IO_13	SIG IO_37		
33	GND IO_14	GND IO_38	K_18	
34	SIG IO_14	SIG IO_38		
35	GND IO_15	GND IO_39	K_19	
36	SIG IO_15	SIG IO_39		
37	GND IO_16	GND IO_40	K_20	
38	SIG IO_16	SIG IO_0		
39	GND IO_17	GND IO_41	K_21	
40	SIG IO_17	SIG IO_41		
41	GND IO_18	GND IO_42	K_22	
42	SIG IO_18	SIG IO_42		
43	Sens_2_GND	VDD SPI-Interface	K_23	
44	Suppl_2_GND		K_24	
45	Suppl_2_GND			
46	Sens_2_POS		K_25	
47	Suppl_2_POS		K_26	
48	Suppl_2_POS			
49	GND IO_19	GND IO_43	K_27	
50	SIG IO_19	SIG IO_43		
51	GND IO_20	GND IO_44	K_28	
52	SIG IO_20	SIG IO_44		
53	GND IO_21	GND IO_45	K_29	
54	SIG IO_21	SIG IO_45		
55	GND IO_22	GND IO_46	K_30	
56	SIG IO_22	SIG IO_46		
57	GND IO_23	GND IO_47	K_31	
58	SIG IO_23	SIG IO_47		
59	GND IO_24	GND IO_48	K_32	
60	SIG IO_24	SIG IO_48		

9. Connection diagram X10/X11 as a 4x4 SPI Master Machine

Pin		Neutral name X10	4x4 SpiMaMa Name X10		Neutral name X11	4x4 SpiMaMa Name X11	Cable no.
1	V _{DD} Sensor	GND IO_01			GND IO_25		K_01
2		SIG IO_01	CLK_G1		SIG IO_25	CLK_G3	
3		GND IO_02			GND IO_26		K_02
4		SIG IO_02	R_CLK_G1		SIG IO_26	R_CLK_G3	
5		GND IO_03			GND IO_27		K_03
6		SIG IO_03	MOSI_G1		SIG IO_27	MOSI_G3	
7		GND IO_04			GND IO_28		K_04
8		SIG IO_04	RES_TEST_E_G1		SIG IO_28	RES_TEST_E_G3	
9		GND IO_05			GND IO_29		K_05
10		SIG IO_05	CS_G1_S1		SIG IO_29	CS_G3_S1	
11		GND IO_06			GND IO_30		K_06
12		SIG IO_06	CS_G1_S2		SIG IO_30	CS_G3_S2	
13	V _{DD} Aux	Sens_1_GND			Sens_3_GND		K_07
14		Suppl_1_GND			Suppl_3_GND		K_08
15		Suppl_1_GND			Suppl_3_GND		
16		Sens_1_POS			Sens_3_POS		K_09
17		Suppl_1_POS			Suppl_3_POS		
18		Suppl_1_POS			Suppl_3_POS		K_10
19	V _{DD} Sensor	GND IO_07			GND IO_31		K_11
20		SIG IO_07	CS_G1_S3		SIG IO_31	CS_G3_S3	
21		GND IO_08			GND IO_32		K_12
22		SIG IO_08	CS_G1_S4		SIG IO_32	CS_G3_S4	
23		GND IO_09			GND IO_33		K_13
24		SIG IO_09	MISO_G1_S1		SIG IO_33	MISO_G3_S1	
25		GND IO_10			GND IO_34		K_14
26		SIG IO_10	MISO_G1_S2		SIG IO_34	MISO_G3_S2	
27		GND IO_11			GND IO_35		K_15
28		SIG IO_11	MISO_G1_S3		SIG IO_35	MISO_G3_S3	
29		GND IO_12			GND IO_36		K_16
30		SIG IO_12	MISO_G1_S4		SIG IO_36	MISO_G3_S4	
31	V _{DD} Aux	GND IO_13			GND IO_37		K_17
32		SIG IO_13	CLK_G2		SIG IO_37	CLK_G4	
33		GND IO_14			GND IO_38		K_18
34		SIG IO_14	R_CLK_G2		SIG IO_38	R_CLK_G4	
35		GND IO_15			GND IO_39		
36		SIG IO_15	MOSI_G2		SIG IO_39	MOSI_G4	K_19

37	GND IO_16			GND IO_40		K_20
38	SIG IO_16	RES_TEST_E_G2		SIG IO_0	RES_TEST_E_G4	K_21
39	GND IO_17			GND IO_41		
40	SIG IO_17	CS_G2_S1		SIG IO_41	CS_G4_S1	
41	GND IO_18			GND IO_42		K_22
42	SIG IO_18	CS_G2_S2		SIG IO_42	CS_G4_S2	
43	Sens_2_GND					K_23
44	Suppl_2_GND			Suppl_4_GND		K_24
45	Suppl_2_GND			Suppl_4_GND		K_25
46	Sens_2_POS					K_26
47	Suppl_2_POS			Suppl_4_POS		
48	Suppl_2_POS			Suppl_4_POS		
49	GND IO_19			GND IO_43		K_27
50	SIG IO_19	CS_G2_S3		SIG IO_43	CS_G4_S3	K_28
51	GND IO_20			GND IO_44		
52	SIG IO_20	CS_G2_S4		SIG IO_44	CS_G4_S4	
53	GND IO_21			GND IO_45		K_29
54	SIG IO_21	MISO_G2_S1		SIG IO_45	MISO_G4_S1	
55	GND IO_22			GND IO_46		K_30
56	SIG IO_22	MISO_G2_S2		SIG IO_46	MISO_G4_S2	
57	GND IO_23			GND IO_47		K_31
58	SIG IO_23	MISO_G2_S3		SIG IO_47	MISO_G4_S3	
59	GND IO_24			GND IO_48		K_32
60	SIG IO_24	MISO_G2_S4		SIG IO_48	MISO_G4_S4	

10. Connection cable

K_01 .. K_07, K_09, K_11 .. K_23, K_25, K_27 .. K_32	Coaxial cable, 1,3mm diameter
K_08, K_10, K_24, K_26	Litz wire 0,75mm ² 2mm diameter
All cable length =2m, end open	

